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AMENDMENTS TO THE CLAIMS:

This listing of claims will replace all prior versions, and listings, of claims in the application:

LISTING OF CLAIMS:

Claims 1-12 (canceled).

Claim 13 (currently amended): A lid material for a lid which is to be fuse-bonded to a peripheral upper surface of a case having an open top and a housing space for an electronic component, the lid material comprising:

a core layer;

a nickel-based metal layer composed of a nickel-based metal foil mainly comprising nickel, an entire thickness of the nickel-based metal layer being press- and diffusion-bonded onto the core layer with no portion of the nickel-based metal layer being electroplated; and

a brazing material layer press-bonded onto the nickel-based metal layer,

wherein the nickel-based metal layer has a maximum-to-minimum thickness ratio $T1/T2$ of 1.4 to 15.

Claim 14 (original): A lid material as set forth in claim 13, wherein the core layer is composed of an iron-nickel-based alloy mainly comprising iron and nickel.

Claim 15 (original): A lid material as set forth in claim 13, wherein the brazing material layer is composed of a soft brazing material having a melting point of not higher than 450°C.

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Claim 16 (original): A lid material as set forth in claim 14, wherein the brazing material layer is composed of a soft brazing material having a melting point of not higher than 450°C.

Claim 17 (original): A lid material as set forth in claim 15, wherein the soft brazing material is free from lead.

Claim 18 (original): A lid material as set forth in claim 16, wherein the soft brazing material is free from lead.

Claim 19 (currently amended): An electronic component package comprising:
a case having an open top and a housing space for an electronic component;
and

a lid provided on the top of the case, the lid comprising a core layer, a nickel-based metal layer composed of a nickel-based metal foil mainly comprising nickel, an entire thickness of the nickel-based metal layer being press- and diffusion-bonded onto the core layer with no portion of the nickel-based metal layer being electroplated, and a brazing material layer press-bonded onto the nickel-based metal layer, the nickel-based metal layer having a maximum-to-minimum thickness ratio T1/T2 of 1.4 to 15,

wherein the brazing material layer of the lid is fuse-bonded to a peripheral upper surface of the case.

Claim 20 (original): An electronic component package as set forth in claim 19, wherein the core layer is composed of an iron-nickel-based alloy mainly comprising iron and nickel.

Claim 21 (original): An electronic component package as set forth in claim 19, wherein the brazing material layer is composed of a soft brazing material having a

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melting point of not higher than 450°C.

Claim 22 (original): An electronic component package as set forth in claim 20, wherein the brazing material layer is composed of a soft brazing material having a melting point of not higher than 450°C.

Claim 23 (original): An electronic component package as set forth in claim 21, wherein the soft brazing material is free from lead.

Claim 24 (original): An electronic component package as set forth in claim 22, wherein the soft brazing material is free from lead.

Claim 25 (previously presented): A lid material as set forth in claim 13, wherein the brazing material layer is roll-pressed onto the nickel-based metal layer.

Claim 26 (previously presented): A lid material as set forth in claim 13, wherein the nickel-based metal layer has an average thickness of about 5 μm to about 50 μm .

Claim 27 (previously presented): An electronic component package as set forth in claim 19, wherein the brazing material layer is roll-pressed onto the nickel-based metal layer.

Claim 28 (previously presented): An electronic component package as set forth in claim 19, wherein the nickel-based metal layer has an average thickness of about 5 μm to about 50 μm .

Claim 29 (new): A lid material for a lid which is to be fuse-bonded to a peripheral upper surface of a case having an open top and a housing space for an electronic

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component, the lid material comprising:

a core layer;

a nickel-based metal layer composed of a nickel-based metal mainly comprising nickel, an entire thickness of the nickel-based metal layer being press- and diffusion-bonded onto the core layer; and

a brazing material layer press-bonded onto the nickel-based metal layer such that the total thickness of the core layer, the nickel-based metal layer, and the brazing material layer is reduced by a ratio of between about 30% to about 60%;

wherein the nickel-based metal layer has a maximum-to-minimum thickness ratio $T1/T2$ of 1.4 to 15.

Claim 30 (new): A lid material as set forth in claim 29, wherein the core layer is composed of an iron-nickel-based alloy mainly comprising iron and nickel.

Claim 31 (new): A lid material as set forth in claim 29, wherein the brazing material layer is composed of a soft brazing material having a melting point of not higher than 450°C.

Claim 32 (new): A lid material as set forth in claim 30, wherein the brazing material layer is composed of a soft brazing material having a melting point of not higher than 450°C.

Claim 33 (new): A lid material as set forth in claim 31, wherein the soft brazing material is free from lead.

Claim 34 (new): A lid material as set forth in claim 32, wherein the soft brazing material is free from lead.

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Claim 35 (new): A lid material as set forth in claim 29, wherein the brazing material layer is roll-pressed onto the nickel-based metal layer.

Claim 36 (new): A lid material as set forth in claim 29, wherein the nickel-based metal layer has an average thickness of about 5 μm to about 50 μm .

Claim 37 (new): An electronic component package comprising:
a case having an open top and a housing space for an electronic component;
and

a lid provided on the top of the case, the lid comprising a core layer, a nickel-based metal layer composed of a nickel-based metal mainly comprising nickel, an entire thickness of the nickel-based metal layer being press- and diffusion-bonded onto the core layer, and a brazing material layer press-bonded onto the nickel-based metal layer such that the total thickness of the core layer, the nickel-based metal layer, and the brazing material layer is reduced by a ratio of between about 30% to about 60%, the nickel-based metal layer having a maximum-to-minimum thickness ratio T_1/T_2 of 1.4 to 15;

wherein the brazing material layer of the lid is fuse-bonded to a peripheral upper surface of the case.

Claim 38 (new): An electronic component package as set forth in claim 37, wherein the core layer is composed of an iron-nickel-based alloy mainly comprising iron and nickel.

Claim 39 (new): An electronic component package as set forth in claim 37, wherein the brazing material layer is composed of a soft brazing material having a melting point of not higher than 450°C.

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Claim 40 (new): An electronic component package as set forth in claim 38, wherein the brazing material layer is composed of a soft brazing material having a melting point of not higher than 450°C.

Claim 41 (new): An electronic component package as set forth in claim 39, wherein the soft brazing material is free from lead.

Claim 42 (new): An electronic component package as set forth in claim 40, wherein the soft brazing material is free from lead.

Claim 43 (new): An electronic component package as set forth in claim 37, wherein the brazing material layer is roll-pressed onto the nickel-based metal layer.

Claim 44 (new): An electronic component package as set forth in claim 37, wherein the nickel-based metal layer has an average thickness of about 5 μm to about 50 μm .